

**MOLYBDENUM SPUTTERING TARGET, METHOD FOR
MANUFACTURING SAME, AND FILM FORMING METHOD
FOR MOLYBDENUM FILM**

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ABSTRACT

Disclosed is a molybdenum sputtering target having a content of metal impurities of 100 ppm by mass or less, a tungsten content of 50 ppm by mass or less, and an oxygen concentration of 50 ppm by mass or less.

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[Fig. 1]